SNN55-HXP SB

Form-In-Place

SNN55-HXP SB FORM-IN-PLACE

A lower dimension compliant, silver/nickel filled heat cure silicone Form-In-Place grade.

Thanks to its unique filler technology, SNN55-HxP SB can be dispensed consistently below 0.4 mm to comply with challenging compact design application.

SNN55HXP is a Silver/ Nickel filled silicone paste with low hardness contributing to relatively low deflection force when compressing the gasket. It shows very good shielding performance along with good compression set ending in overall long term reliability.

Laird’s Form-In-Place is an automated system for dispensing conductive elastomer EMI shielding and grounding gaskets onto metal or plastic substrates. This product is particularly ideal for small size equipment in Data/Telecom application and for portable devices where space is a constraint

All Laird Paste can be dispensed to triangle shape cross section directly.

TYPICAL VALUES

CATEGORIES	TEST METHOD	UNITS	SNN55-HXP SB
Elastomer			Silicone
Filler type			Silver/Nickel
ELECTRICAL PROPERTIES			
Volume Resistivity		ohm-cm	0.004
Shielding Effectiveness	MIL-DTL-83528C		
200 MHz to 10 GHz	Para. 4.5.12	dB	>100
PHYSICAL PROPERTIES			
Hardness	ASTM D2240	Shore A	55
Density (cured)	ASTM D792	g/cm^3	3.8
Compression Set	ASTM D395	%	15
Adhesion Strength (Al)	LT-FIP-CLE-03		>150
Compression-Deflextion (a)	LT-FIP-CLE-07		
at 20% compression		lb/in	2.5
at 40% compression		lb/in	8.5
Temperature Range		°C	-50°C to 125°C
UL Flammability Rating	UL94(between Al)		V0 (pending)
CURING REQUIREMENTS			
Cure Conditions		125 °c min	
Full Cure(b)		1.5 hours	

(a) Compression-deflection bead size 0.7mm (H) × 0.80mm (W)

(b) Time to effectively cure a bead will necessarily depend on individual conditions, including but not limited to bead size, shield size and weight, oven capacity, and oven ramp-rates.

USA: +1.866.928.8181

Europe: +49.0.8031.2460.0

Asia: +86.755.2714.1166

www.laird.com

EMI-DS-SNN55-HXP SB 122616